## PT79SR100 Series

-1.5 Amp Negative Step-Down Integrated Switching Regulator



### SLTS061A

(Revised 6/30/2000)



Characteristics			PT79SR	PT79SR100 SERIES			
(T <sub>a</sub> = 25°C unless noted)	Symbols Conditions		Min	Тур	Max	Units	
Output Current	Io	Over V <sub>in</sub> range	-0.1*	_	-1.5	Α	
Short Circuit Current	$I_{sc}$	Vin=Vo-4V		-3.5	_	Apk	
Input Voltage Range	$V_{in}$	$\begin{array}{llllllllllllllllllllllllllllllllllll$	-9 -19	_	-30 -30	V V	
Output Voltage Tolerance	$\Delta V_{o}$	Over Vin range, I <sub>o</sub> =-1.5 A T <sub>a</sub> =-20°C to shutdown	_	±1.0	±3.0	$%V_{0}$	
Line Regulation	Reg <sub>line</sub>	Over V <sub>in</sub> range		±1.0	±2.0	$%V_{o}$	
Load Regulation	Regload	$-0.1 \le I_o \le -1.5 \text{ A}$		±0.5	±1.0	$%V_{o}$	
V <sub>o</sub> Ripple/Noise	$V_n$	V <sub>in</sub> =-15V, I <sub>o</sub> =-1.0 A,V <sub>o</sub> =-5V	_	35	_	$mV_{pp}$	
Transient Response	t <sub>tr</sub>	50% load change Vo=overshoot/undershoot	_	100 30	_	μSec %Vo	
Efficiency	η	V <sub>in</sub> =-10V, I <sub>o</sub> =-1.0A, V <sub>o</sub> =-5V	_	85	_	%	
Switching Frequency	$f_{ m o}$	Over Vin and Io ranges	0.95	1.0	1.05	MHz	
Absolute Maximum Operating Temperature Range	T <sub>a</sub>		-40	-	+85	°C	
Recommended Operating Temperature Range	Та	Free Air Convection, (40-60LFM) Over $V_{in}$ and $I_o$ ranges	-40	_	+60**	°C	
Thermal Resistance	$\theta_{ja}$	Free Air Convection, (40-60LFM)	_	45	_	°C/W	
Temperature Coefficient	T <sub>c</sub>	Over Vin and Io ranges	_	±0.5	±1.5	mV/°C	
Storage Temperature	Ts	_	-40	_	+125	°C	
Mechanical Shock		Per Mil-STD-883D, Method 2002.3	_	500	_	G's	
Mechanical Vibration	—	Per Mil-STD-883D, Method 2007.2, 20-2000 Hz, soldered in a PC board	—	5	—	G's	
Weight	_	_		7.0	_	Grams	

\* ISR will operate down to no load with reduced specifications.

\*\* See Thermal Derating chart.



# **Typical Characteristics**

-1.5 Amp Negative Step-Down Integrated Switching Regulator



Note 1: All data listed in the above graphs, except for derating data, has been developed from actual products tested at 25°C. This data is considered typical data for the ISR. Note 2: Thermal derating graphs are developed in free air convection cooling of 40-60 LFM soldered in a printed circuit board. (See Thermal Application Notes.)

TEXAS **TRUMENTS** www.ti.com

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### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
PT79SR105H	ACTIVE	SIP MOD ULE	EFA	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
PT79SR105S	ACTIVE	SIP MOD ULE	EFC	3	25	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM
PT79SR105T	ACTIVE	SIP MOD ULE	EFT	3	25	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM
PT79SR105V	ACTIVE	SIP MOD ULE	EFD	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
PT79SR106S	ACTIVE	SIP MOD ULE	EFC	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
PT79SR108H	ACTIVE	SIP MOD ULE	EFA	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
PT79SR108S	ACTIVE	SIP MOD ULE	EFC	3	25	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM
PT79SR108V	ACTIVE	SIP MOD ULE	EFD	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
PT79SR109H	ACTIVE	SIP MOD ULE	EFA	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
PT79SR109S	ACTIVE	SIP MOD ULE	EFC	3	25	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM
PT79SR112H	ACTIVE	SIP MOD ULE	EFA	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
PT79SR112S	ACTIVE	SIP MOD ULE	EFC	3	25	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM
PT79SR112T	ACTIVE	SIP MOD ULE	EFT	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
PT79SR112V	ACTIVE	SIP MOD ULE	EFD	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
PT79SR115H	ACTIVE	SIP MOD ULE	EFA	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
PT79SR115S	ACTIVE	SIP MOD ULE	EFC	3	25	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM
PT79SR115T	ACTIVE	SIP MOD ULE	EFT	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
PT79SR115V	ACTIVE	SIP MOD ULE	EFD	3	25	Pb-Free (RoHS)	Call TI	N / A for Pkg Type
PT79SR152H	ACTIVE	SIP MOD ULE	EFA	3	25	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM
PT79SR152S	ACTIVE	SIP MOD ULE	EFC	3	25	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM
PT79SR152ST	ACTIVE	SIP MOD ULE	EFC	3	200	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM
PT79SR152V	ACTIVE	SIP MOD ULE	EFD	3	25	Pb-Free (RoHS)	Call TI	Level-1-215C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.



**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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